Atty. Docket No. PIA31222/DBE/US

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

	Jennie Heaton
	ed with the United States Postal Service as Express Mail No. dressed to Commissioner for Patents, Washington, D.C. 20231. By:
FOR: Method for Packaging a Semiconductor Device	
FILED: HEREWITH	: EXAMINER:
SERIAL NO: NEW APPLICATION	:
Byoung Young KANG	: GROUP ART UNIT:
IN RE APPLICATION OF:	:

REQUEST FOR PRIORITY UNDER 35 U.S.C. 119(a)-(b) AND 37 C.F.R. 1.55

COMMISSIONER FOR PATENTS WASHINGTON, D.C. 20231

SIR:

Applicant respectfully requests under the Paris Convention for the Protection of Intellectual Property the benefit of the filing date of the prior foreign application(s) identified below:

Serial No.

Filing Date

Country of Filing

10-2002-0086651

December 30, 2002

Republic of KOREA

A certified copy of the priority application will be filed before any U.S. patent issues from the above-captioned application.

Respectfully submitted,

Andrew D. Fortney, Ph.D.

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